

EvoTRAC-S1901 PLATFORM



Forced Air Cooled



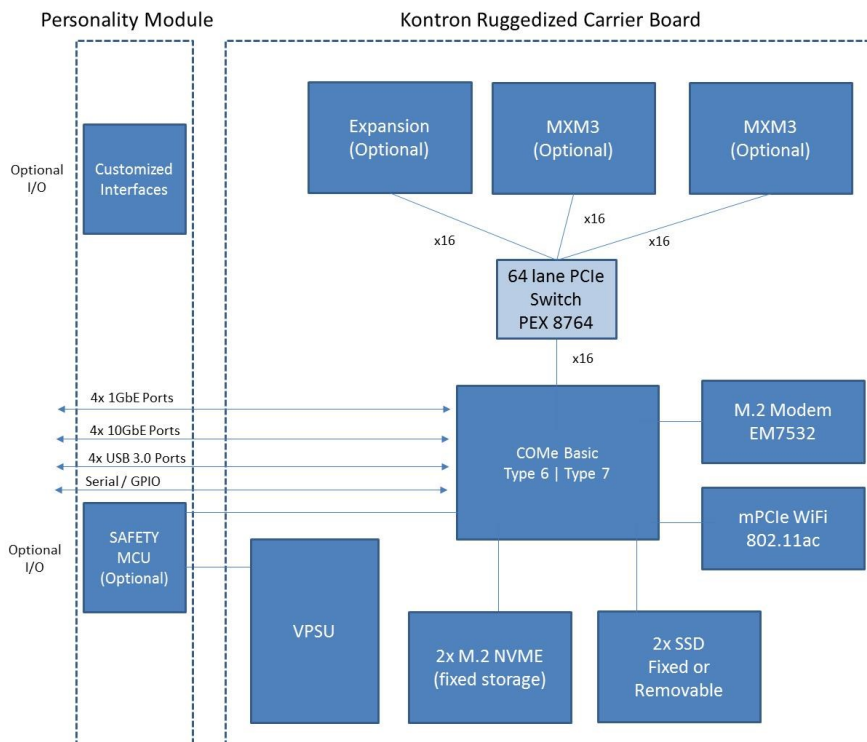
Conduction Cooled

Application Ready Platform for In-Vehicles Systems

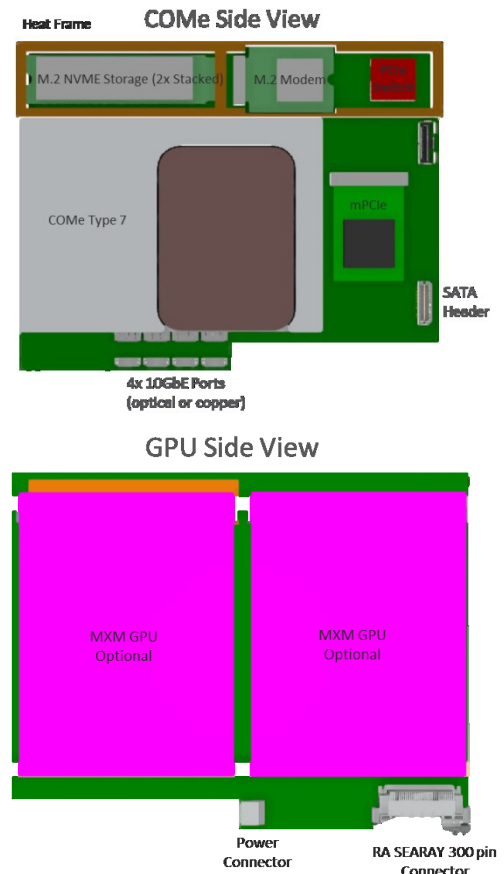
- ▶ ComExpress Intel® High Performance Processor
- ▶ expansion slots for multiple GPU, FPGA accelerators, or video modules
- ▶ multiple I/O high speed interfaces and high capacity storage options
- ▶ wireless connectivity options for cellular and wifi
- ▶ ruggedized & modular platform for in-vehicle deployment

TECHNICAL INFORMATION

DIMENSIONS	13.0"W x 7.0"D x 3.25"H
COMe PROCESSOR	COMe-bDV7 (Denverton) COMe-bKL6 (Kabylake) COMe-bSL6 (Skylake) COMe-bL6 (Broadwell) Up to 64GB RAM (processor dependent)
MXM3 GPU	MXM GT1080 (150W), MXM P5000 (100W), other MXM modules possible
STORAGE	2x M.2 NVME 2x 2.5" SSD (fixed or removable)
ETHERNET PORTS	4x 1GbE 4x 10GbE (Copper or Optical) Ethernet Switch (optional)
PCI-EXPRESS	(3) x1 PCIe internal (1) x16 PCIe connector header (optional)
USB	4x USB 3.0/2.0 ports
WIRELESS	Cellular (M.2) connectivity WiFi (mPCIe) connectivity
SERIAL	2x RS232
DISCRETES	8x direct GPIO 40x GPIO (optional)
POWER	Input Voltage: 10 – 16VDC (12VDC nominal) Power Consumption: up to 350W (configuration dependent)
COOLING	Conduction Cooled or Air Cooled Assist (configuration dependent)
OPERATING SYSTEM	Linux Ubuntu 16.04, LTS, 64-Bit (installed)



System Architecture | Configurable Options For Project Based Solutions



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